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AMENDMENT TRANSMITTAL LETTER			Docket No. SON-2998	
Application No. 10/823,572 Conf. No. 4816	Filing Date April 14, 2004	Examiner T.Q. Phan	Art Unit 2827	

Applicant(s): Kou Nagata, et al.

Invention: SEMICONDUCTOR MEMORY APPARATUS AND SELF-REPAIR METHOD

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	18	- 20 =		x	
Independent Claims	3	- 3 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

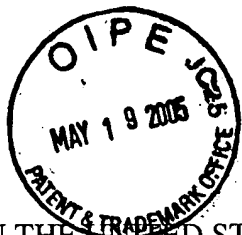
- ☒ Large Entity ☐ Small Entity
- ☒ No additional fee is required for this amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.
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- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 18-0013
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- ☒ Credit any overpayment.
- ☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

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Dated: May 19, 2005

SON-2998



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kou Nagata, et al.

Application No.: 10/823,572

Filed: April 14, 2004

For: SEMICONDUCTOR MEMORY APPARATUS
AND SELF-REPAIR METHOD

Art Unit: 2827

Conf. No. 4816

Examiner: T.Q. Phan

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In full and timely response to the Office Action dated March 2, 2005, please amend the above-identified U.S. patent application as follows: